

MA3G655 (MA655)

Silicon planar type (cathode common)

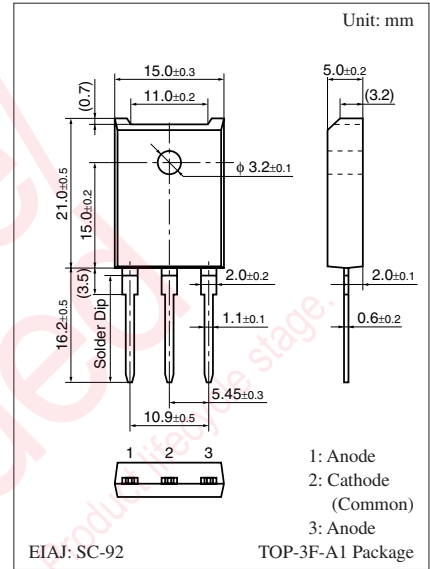
For high-frequency rectification

■ Features

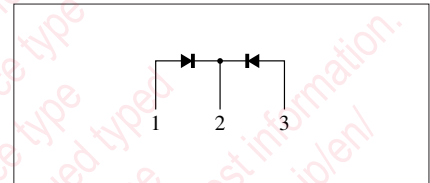
- High reverse voltage V_R
- Low forward voltage V_F
- Fast reverse recovery time t_{rr}

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	300	V
Non-repetitive peak reverse surge voltage	V_{RSM}	300	V
Forward current (Average)	$I_{F(AV)}$	20	A
Non-repetitive peak forward surge current	I_{FSM}	150	A
Junction temperature	T_j	-40 to +150	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +150	$^\circ\text{C}$



Internal Connection



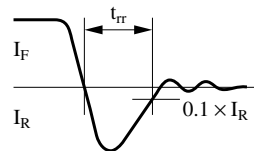
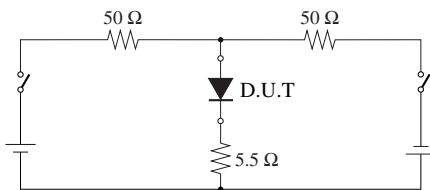
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10\text{ A}, T_C = 25^\circ\text{C}$			1.0	V
Repetitive peak reverse current	I_{RRM1}	$V_{RRM} = 300\text{ V}, T_C = 25^\circ\text{C}$			20	μA
		$V_{RRM} = 300\text{ V}, T_j = 150^\circ\text{C}$			5	mA
Reverse recovery time *	t_{rr}	$I_F = 1\text{ A}, I_R = 1\text{ A}$			50	ns
Thermal resistance (j-c)	$R_{th(j-c)}$				1.5	$^\circ\text{C/W}$
Thermal resistance (j-a)	$R_{th(j-a)}$				40	$^\circ\text{C/W}$

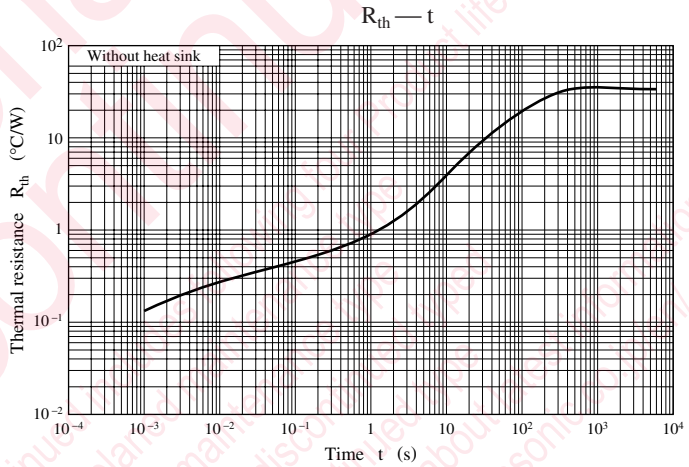
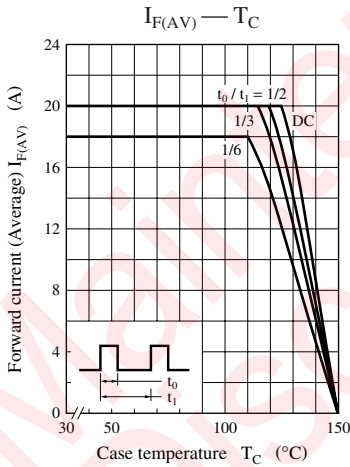
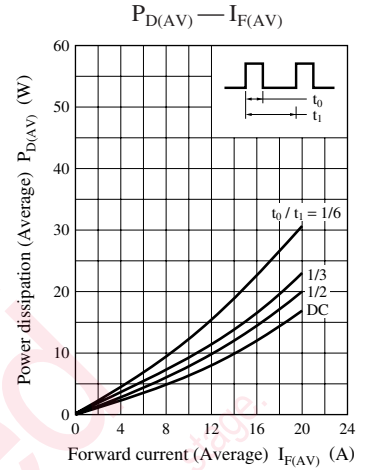
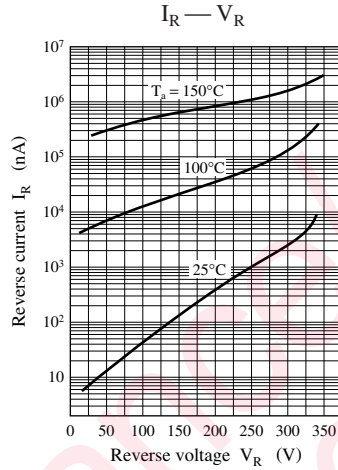
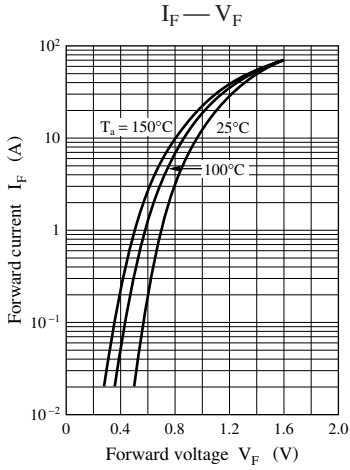
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 10 MHz.

3. *: t_{rr} measurement circuit



Note) The part number in the parenthesis shows conventional part number.



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